

FIG. 1 (PRIOR ART)

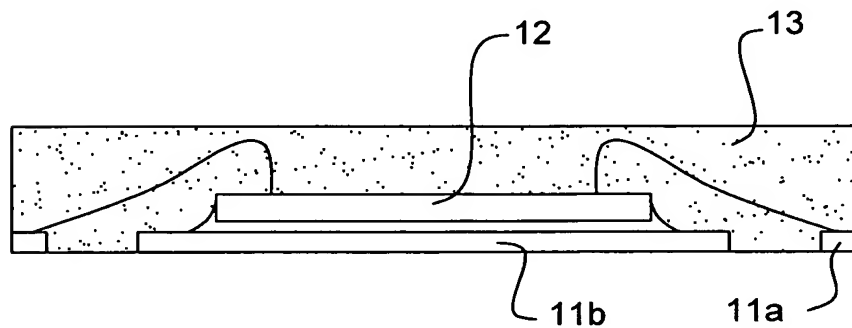


FIG. 2 (PRIOR ART)

LEADLESS SEMICONDUCTOR PACKAGE AND MANUFACTURING METHOD THEREOF

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100

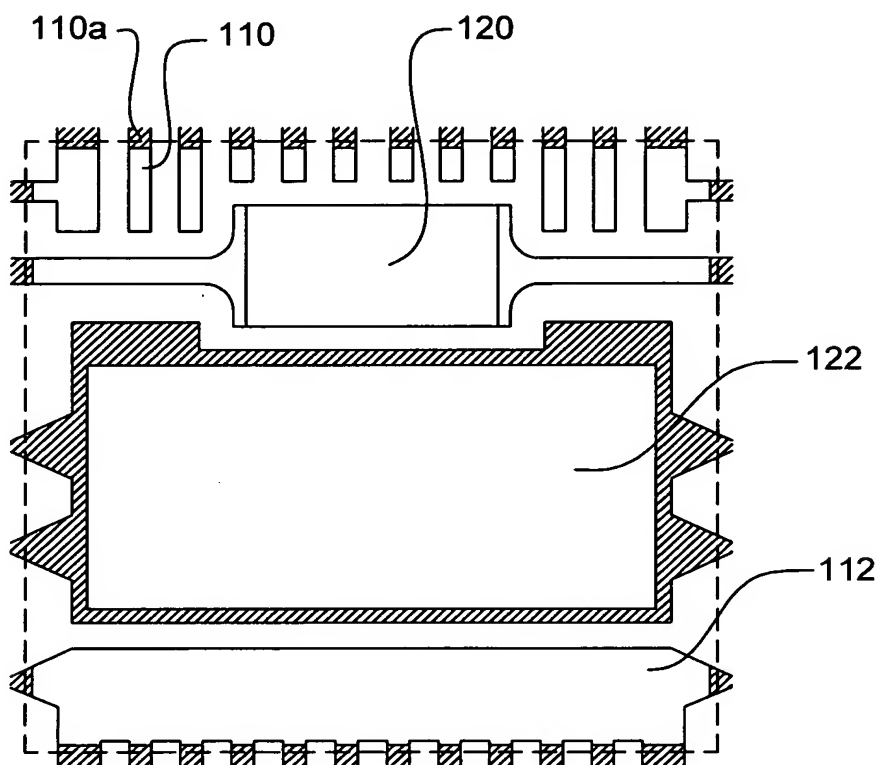


FIG. 3

200

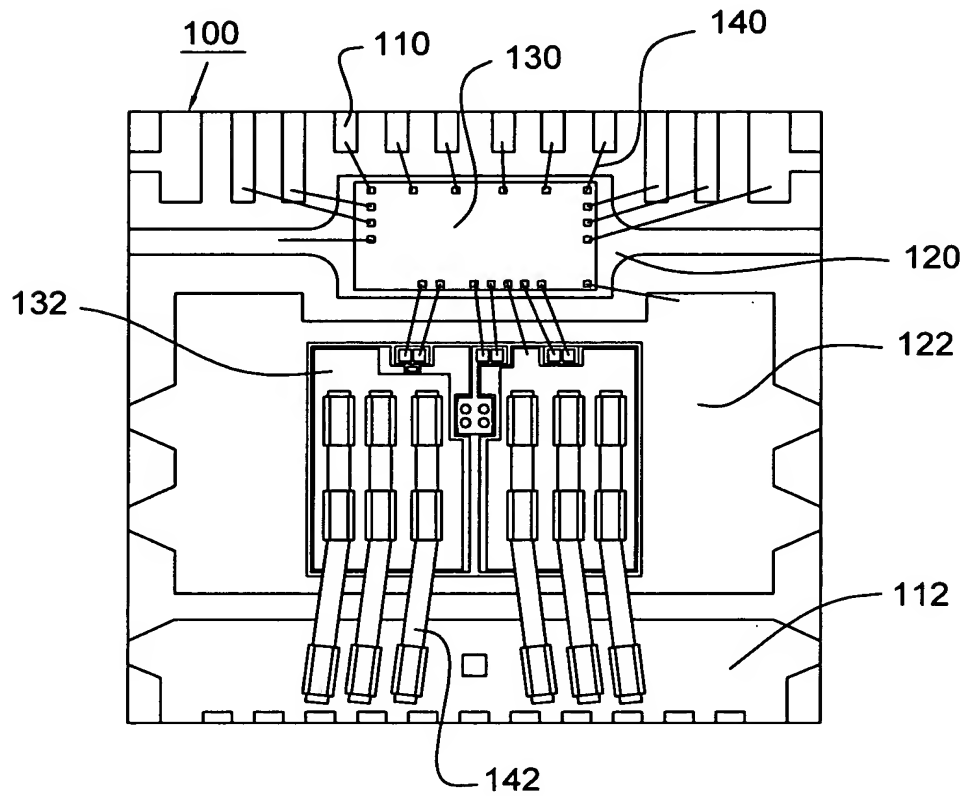


FIG. 4

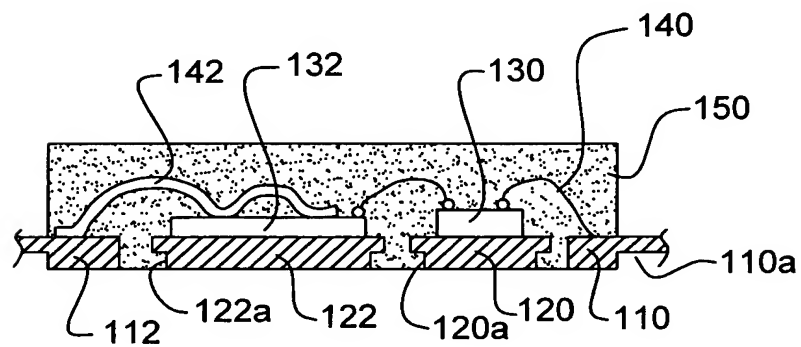


FIG. 5